



RECEIVED
NOV 07 2003
TC 1700

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Emami, et al.

Serial No.: 09/727,133

Confirmation No.: 2919

Filed: November 29, 2000

For: Planarized Copper Cleaning for
Reduced Defects

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

§
§
§ Group Art Unit: 1763
§
§ Examiner: George A. Goudreau
§
§
§
§
§
§

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>October 31, 2003</u> , with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
<u>10/31/03</u> Date	<u>Keith M. Tackett</u> Signature

STATEMENT OF COMMON OWNERSHIP

The present application (Serial No. 09/727,133; hereinafter the "Application") and U.S. Patent Serial No. 6,436,302 *Li et al.*, were, at the time the invention of the Application was made, owned by the same person, or subject to an obligation of assignment to the same person, Applied Materials, Inc.

Respectfully submitted,

Keith M. Tackett
Keith M. Tackett
Registration No. 32,008
MOSER, PATTERSON & SHERIDAN, L.L.P.
3040 Post Oak Blvd., Suite 1500
Houston, TX 77056
Telephone: (713) 623-4844
Facsimile: (713) 623-4846
Attorney for Applicant(s)